

Specification

for

LCD Module

TS240128D-1

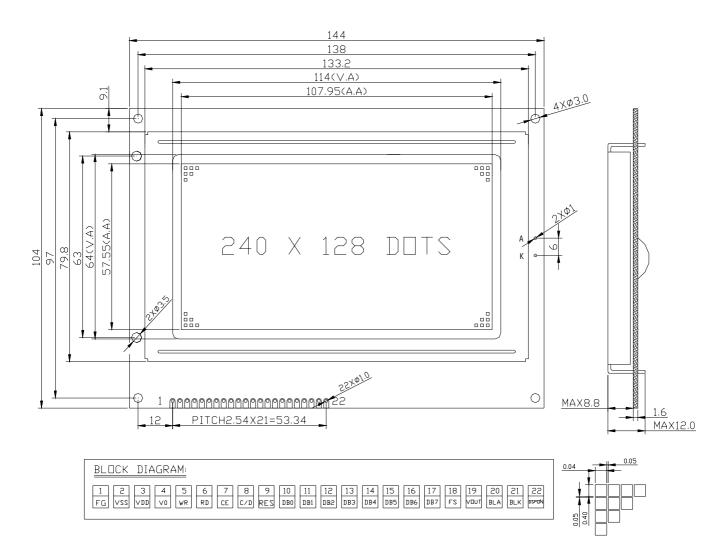
PRODUCT SPECIFICATIONS

- PHYSICAL DATA
- EXTERNAL DIMENSIONS
- BLOCK DIAGRAM
- ABSOLUTE MAXIMUM RATINGS
- ELECTRICAL CHARACTERISTICS
- FL BACKLIGHT CHARACTERISTICS
- OPERATING PRINCIPLES & METHODS
- ELECTRO-OPTICAL CHARACTERISTICS
- INTERFACE PIN CONNECTIONS
- RELIABILITY
- QUALITY GUARANTEE
- INSPECTION CRITERIA
- PRECAUTIONS FOR USING LCD MODULES
- USING LCD MODULES

■ PHYSICAL DATA

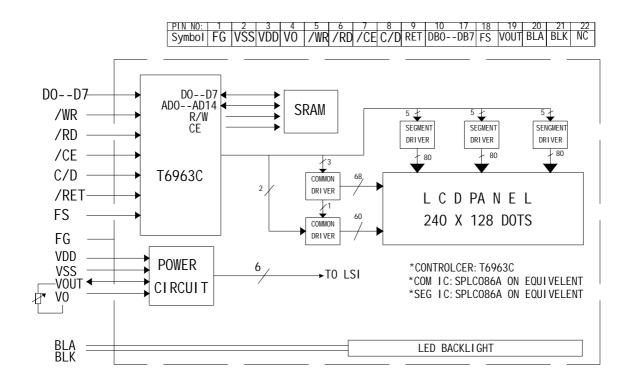
Item	Contents	Unit
LCD type	STN	
LCD duty	1/128	
LCD bias	1/12	
Viewing direction	6	o'clock
Module size (W×H×T)	$144 \times 104 \times 12.0 \text{MAX}$	mm
Viewing area (W×H)	114 × 64 (4.49" × 2.52")	mm
Number of dots	240 × 128	dots
Dot size (W×H)	$0.40 \times 0.40 \ (0.016'' \times 0.016'')$	mm
Dot pitch (W×H)	$0.45 \times 0.45 \ (0.018'' \times 0.018'')$	mm

■ EXTERNAL DIMENSIONS





■ BLOCK DIAGRAM



■ ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Min	Max	Unit
Supply voltage for logic	VDD	-0.3	7.0	V
Supply voltage for LCD	VDD - VO	-0.3	28	V
Input voltage	VI	-0.3	VDD+0.3	V
Operating temperature	TOP	0	50	°C
Storage temperature	TST	-10	60	°C

■ ELECTRICAL CHARACTERISTICS (VDD = +5V±10%, VSS = 0V, Ta = 25°C)

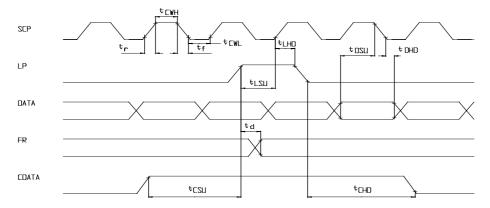
DC Characteristics

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Supply voltage for logic	VDD		4.5	5.0	5.5	V
Supply current for logic	IDD			16	22	mA
		0°C	17.0	18.0	19.0	V
Operating voltage for LCD	VDD - VO	25°C	16.5	17.5	18.5	V
		50°C	15.9	16.9	17.9	V
Input voltage 'H'level	VIH		VDD - 2.2		VDD	V
Input voltage 'L'level	VIL		0		0.8	V

AC Characteristics

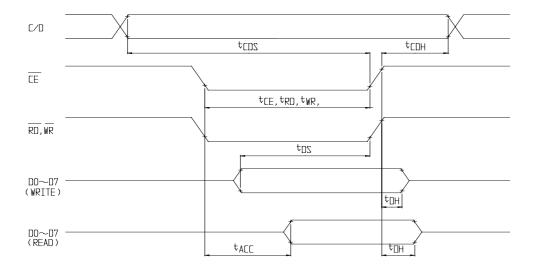
• AC Characteristics (1)

Parameter	Symbol	Min	Max	Unit
Operating frequency	fscp		2.75	MHz
SCP pulse width	tcwн, tcwl	150		ns
SCP rise/fall time	tr, tf		30	ns
LP set up time	t lsu	150	290	ns
LP hold time	t lhd	5	40	ns
Data set up time	t dsu	170		ns
Data hold time	t dhd	80		ns
FR delay time	t d	0	90	ns
CDATA set up time	t csu	450	850	ns
CDATA hold time	t chd	450	950	ns



• AC Characteristics (2)

Parameter	Symbol	Min	Max	Unit
C/D set up time	tcds	100		ns
C/D hold time	t CDH	10		ns
CE, RD, WR pulse width	tce, trd, twr	80		ns
Data set up time	tds	80		ns
Data hold time	tdн	40		ns
Access time	tacc		150	ns
Output hold time	tон	10	50	ns



■ FL BACKLIGHT CHARACTERISTICS

Absolute Maximum Ratings

Item	Symbol	Conditions	Standard			Unit
			Min.	Typ.	Max.	
Circuit voltage	V_{S}				240	Vrms
Lamp current	$ m I_{FL}$	Ta= 25°C			6	mArms

Electrical Characteristics

Item	Symbol	Conditions		Standard		
			Min.	Тур.	Max.	
Lamp voltage*1	V_{FL}	Ta= 25°C	195	220	235	Vrms
Starting voltage*2	V_{S}	Ta= 0°C			400	Vrms
Lamp current*1	I_{FL}	Ta= 25°C	4.0	5.0	6.0	mArms
Frequency*1	f_{FL}	Ta= 25°C	50		60	kHz

^{*1} FL inverter: 13585AQ17

Optical Characteristics

Item	Symbol	Conditions	Standard		Unit	
			Min.	Typ.	Max.	
Surface brightness*1*2*4	Bp	Ta= 25 ±3°C	80	110		cd/m ²
Distribution of brightness*1*3	Вр	30~85%RH			30	%

*1 Measurement 30 minutes after turning on of FL tube

FL inverter: 13585AQ17

FL inverter output voltage and freguency: 220V, 59kHz

LCD driving conditions: Optimum Vopr

LCD display pattern: ALL off display (all data="L")

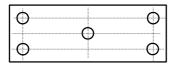
- *2 Initial brightness of LCD panel center
- *3 Definition of Bp (Distribution of brightness)

 $Bp=(Bp(max.) - Bp(min.))/Bp(max.) \times 100\%$

Bp(max.)=Maximun brightness of 5 measuring points

Bp(min.)=Minimem brightness of 5 measuring points

5 measuring points:



*4 Ambient temperature affects brightness of FL tube. The reason is that radiation efficiency is depends on steam pressure of mercury enclosed in the tube. Practically the brightness is low in the cool. As the steam pressure of mercury is also low just after turning on of FL tube, the brightness is low. The heat generated by FL tube will raise temperature on the tube surface, then brightness will increase with a rise in mercury steam pressure.

Life

Item	Conditions	Standard		Unit
		Min.	Max.	
Life*1	Ta= 25 ±3°C	15000		hrs

^{*1} FL driving condition: I_{FL} (Lamp current)=5 mArms

Time until the decreases to half of the initail brightness, or time until "not lit" because of increase in FL discharge start voltage.

^{*2} The voltage capable of starting discharge and keeping stable sischarge. When the voltage gradually increases, glow discharge will increase and FL tube terminals will be connected electrecally.

■ OPERATING PRINCIPLES & METHODS

Flowchart of Communications with MPU

• Status Read

Before sending data (Read/Write) command, it is necessary to check the status.

Status check

Status of T6963C can be read from data lines.

 RD
 L

 WR
 H

 CE
 L

 C/D
 H

 D0-D7
 Status word

T6963C status word format is following.

MSB							LSB
STA7	STA6	STA5	STA4	STA3	STA2	STA1	STA0
D7	D6	D5	D4	D3	D2	D1	D0

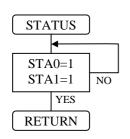
STA0	Check capability of command execution	0 : Disable
		1 : Enable
STA1	Check capability of data read/write	0 : Disable
		1 : Enable
STA2	Check capability of auto mode data read	0 : Disable
		1 : Enable
STA3	Check capability of auto mode data write	0 : Disable
		1 : Enable
STA4	Not use	
STA5	Check capability of controller operation	0 : Disable
		1 : Enable
STA6	Error flag. Using screen peek/copy command	0 : No error
		1 : Error
STA7	Check the condition blink	0 : Display off
		1 : Normal display

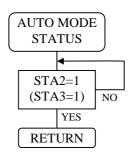
Note 1: It is necessary to check STA0 and STA1 at the same time. The error is happened by sending data at executing command.

Note 2: The status check will be enough to check STA0/STA1.

Note 3: STA2/STA3 are valid in auto mode STA0/STA1 are invalid.

Status checking flow



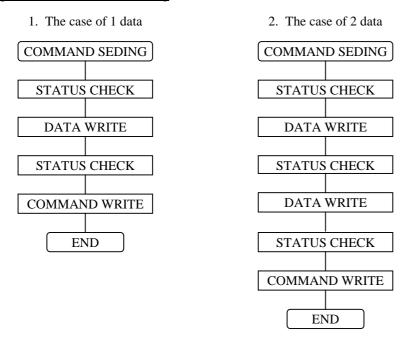


Note 4: It is impossible to save status check in the case of command of MSB0. To have the delay time cannot be save status check. The interrupt of hardware is happened at the end of lines. If command of MSB0 is sent in this period, the command executing is waited. The state of waiting doesn't be known without to check status. The sending next command or data is disregarded or rewrites data of waiting command.

• Data Set

In T6963C, the data have been set and command executes.

The order of procedure of command sending



Note: In case of over 2 data sending, the last data (or last 2 data) is valid.

Description of Command

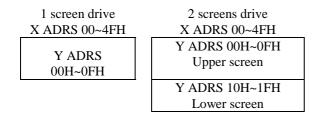
• Register Set

Code	Hex	Function	D1	D2
00100001	21H	Cursor Pointer Set	X ADRS	Y ADRS
00100010	22H	Offset Register Set	Data	00H
00100100	24H	Address Pointer Set	Low ADRS	High ADRS

(1) Cursor Pointer Set

The position of cursor is specified by X ADRS, Y ADRS. The cursor position is moved only by this command. The cursor pointer doesn't have the function of increment and decrement. The shift of cursor are set by this command. X ADRS, Y ADRS are specified following.

X ADRS 00H~4FH (Lower 7bits are valid) Y ADRS 00H~1FH (Lower 5bits are valid)



(2) Offset Register Set

The offset register is used to determine external character generator RAM area.

T6963C has 16 bit address lines as follow.

MSB															LSB
ad15	ad14	ad13	ad12	ad11	ad10	ad9	ad8	ad7	ad6	ad5	ad4	ad3	ad2	ad1	ad0

The upper 5 bit (ad15~ad11) are determined by offset register. The middle 8 bit (ad10~ad3) are determined by character code. The lower 3 bit (ad2~ad0) are determined by vertical counter. The lower 5 bit of D1 (data) are valid. The data format of external character generator RAM.

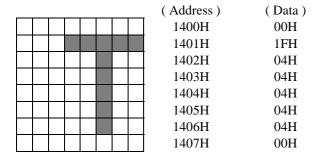
The ralationship of display RAM address and offset register

Data of offset register	CG RAM HEX address(start-end)
00000	0000-07FFH
00001	0800-0FFFH
00010	1000-17FFH
11100	E000-E7FFH
11101	E800-EFFFH
11110	F000-F7FFH
11111	F800-FFFFH

(Example 1)

Offset register 02H Character code 80H

Character generator RAM start address 0001 0100 0000 0000 1 4 0 0



(Example 2)

The relationship of display RAM data and display character

	(RAM Data)	(Character)
ABγDΕζGHIJKLM	21H	A
	22H	В
	83H	γ
	24H	D
	25H	E
	86H	ζ
Display character		

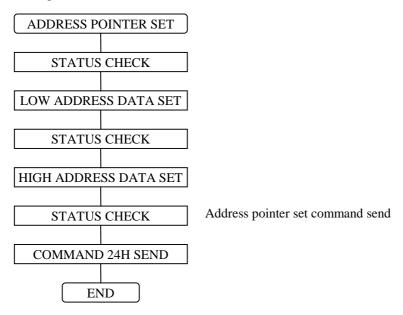
1 7

Note : γ and ζ are displated by character generator RAM.

(3) Address Pointer Set

The address pointer set command is used to indicate the start address for writing (or reading) to external RAM.

The flow chart address pointer set command



• Control Word Set

Code	Hex	Function	D1	D2
01000000	40H	Text home address set	Low address	High address
01000001	41H	Text area set	Columns	00H
01000010	42H	Graphic home address set	Low address	High address
01000011	43H	Graphic area set	Columns	00H

The home address and column size are defined by this command.

(1) Text Home Address Set

The starting address of external display RAM for Text display is defined by this command. The text home address shows the left end and most upper position.

The relationship of external display RAM address and display position

TH	TH+CL
TH+TA	TH+TA+CL
(TH+TA)+TA	TH+2TA+CL
(TH+2TA)+TA	TH+3TA+CL
TH+(n-1)TA	TH+(n-1)TA+CL

TH: Text home address

TA: Text area number (columns)

CL: Columns are fixed by hardware. (pin-programmable)



(Example)

Text home address : 0000H
Text area : 0020H
MD2=H, MD3=H : 32 columns
DUAL=H, MDS=L, MD0=L, MD1=L : 16 lines

20112 11, 1112	3 B, 1112 0 B, 1112	 1100	
H0000	0001H	 001EH	001FH
0020H	0021H	 003EH	003FH
0040H	0041H	 005EH	005FH
0060H	0061H	 007EH	007FH
H0800	0081H	 009EH	009FH
00A0H	00A1H	 00BEH	00BFH
00C0H	00C1H	 00DEH	00DFH
00E0H	00E1H	 00FEH	00FFH
0100H	0101H	 011EH	011FH
0120H	0121H	 013EH	013FH
0140H	0141H	 015EH	015FH
0160H	0161H	 017EH	017FH
0180H	0181H	 019EH	019FH
01A0H	01A1H	 01BEH	01BFH
01C0H	01C1H	 01DEH	01DFH
01E0H	01E1H	 01FEH	01FFH

(2) Graphic Home Address Set

The starting address of external display RAM for Graphic display is defined by this command. The graphic home address shows the left end most upper line.

The relationship of external display RAM address and display position

GH	GH+CL
GH+GA	GH+GA+CL
(GH+GA)+GA	GH+2GA+CL
(GH+2GA)+GA	GH+3GA+CL
GH+(n-1)GA	GH+(n-1)GA+CL

GH: Graphic home address

GA: Graphic area number (colums)

CL: Columns are fixed by hardware. (pin-programmable)

(Example)

Graphic home address : 0000H
Graphic area : 0020H
MD2=H, MD3=H : 32 columns
DUAL=H, MDS=L, MD0=L, MD1=L : 16 lines

H0000	0001H		001EH	001FH
0020H	0021H	•••••	003EH	003FH
0040H	0041H	•••••	005EH	005FH
0060H	0061H	•••••	007EH	007FH
0F80H	0F81H	•••••	0F9EH	0F9FH
0FA0H	0FA1H	•••••	0FBEH	0FBFH
0FC0H	0FC1H	•••••	0FDEH	0FDFH
0FE0H	0FE1H	•••••	0FFEH	0FFFH



(3) Text Area Set

The columns of display are defined by the hardware setting. This command can be used to adjust columns of display.

(Example)

Text home address : 0000H
Text area : 001EH
MD2=H, MD3=H : 32 columns
DUAL=H, MDS=L, MD0=L, MD1=L : 16 lines

D C 1 11, 111D	J-L, MID 0-L, MIL	, 10 m	105		
0000H	0001H		001DH	001EH	001FH
001EH	001FH	•••••	003BH	003CH	003DH
003CH	003DH	••••	0059H	005AH	005BH
005AH	005BH		0077H	0078H	0079H
0078H	0079H	•••••	0095H	0096Н	0097H
0096H	0097H	•••••	00B3H	00B4H	00B5H
00B4H	00B5H		00D1H	00D2H	00D3H
00D2H	00D3H	•••••	00EFH	00F0H	00F1H
00F0H	00F1H	•••••	010DH	010EH	010FH
010EH	010FH	•••••	012BH	012CH	012DH
012CH	012DH	•••••	0149H	014AH	014BH
014AH	014BH	•••••	0167H	0168H	0169H
0168H	0169H	•••••	0185H	0186H	0187H
0186H	0187H		01A3H	01A4H	01A5H
01A4H	01A5H	•••••	01C1H	01C2H	01C3H
01C2H	01C3H		01DFH	01E0H	01E1H
·		•	•	•	

(4) Graphic Area Set

The columns of display are defined by the hardware setting. This command can be used to adjust columns of graphic display.

(Example)

Text home address : 0000H
Text area : 001EH
MD2=H, MD3=H : 32 columns
DUAL=H, MDS=L, MD0=L, MD1=L : 16 lines

	- , - ,				
0000H	0001H	••••	001DH	001EH	001FH
001EH	001FH		003BH	003CH	003DH
003CH	003DH		0059H	005AH	005BH
005AH	005BH	5BH 0077H		0078H	0079H
0E88H	0E89H		0EA5H	0EA6H	0EA7H
0EA6H	0EA6H 0FA7H		0EC3H	0EC4H	0EC5H
0EC4H	0EC4H 0FC5H		0EE1H	0EE1H 0EE2H	
0EE2H	0FE3H	•••••	0EFFH	0F00H	0F01H
1		·	·	i	

 \longrightarrow LCD \longleftarrow

The address in graphic area can be continuous and RAM area can be used without ineffective area, if graphic area is defined the same number as the actual column number of LCD display.

• Mode Set

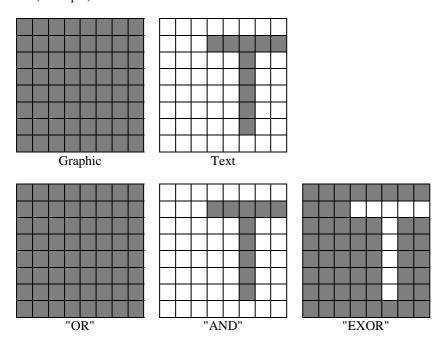
Code	Function	Operand
1000x000	"OR" Mode	
1000x001	"EXOR" Mode	
1000x011	"AND" Mode	
1000x100	"TEXT ATTRIBUTE" Mode	
10000xxx	Internal Character Generator Mode	
10001xxx	External Character Generator Mode	

x: Don't care

The display mode is defined by this command. The display mode don't have changed until to send next this command. Logically "OR", "EXOR", "AND" of text and graphic display can be displayed.

When internal character generator mode is selected, character code 00H~7FH are selected from built-in character generator ROM. The character code 80H~FFH are automatically selected external character generator RAM.

(Example)



Note: Only text display is attributed, because attribute data is located in graphic RAM area.

Attribute function

"Reverse display", "Character blink" and "Inhibit" are called "Attribute". The attribute data is written in the graphic area defined by control word set command. The mode set command selects text display only and graphic display cannot be displayed.

The attribute data of the lst character in text area is written at the lst byte in graphic area, and attribute data of n-th character is written at the n-th byte in graphic area. Attribute function is defined as follow.

Attribute RAM byte	X	X	X	X	d3	d2	d1	d0

d3	d2	d1	d0	Function
0	0	0	0	Normal display
0	1	0	1	Reverse display
0	0	1	1	Inhibit display
1	0	0	0	Blink of normal display
1	1	0	1	Blink of reverse display
1	0	1	1	Blink of inhibit display



• Display Mode

Code	Function	Operand
10010000	Display off	
1001xx10	Cursor on, blink off	
1001xx11	Cursor on, blink on	
100101xx	Text on, graphic off	
100110xx	Text off, graphic on	
100111xx	Text on, graphic on	

1	0	0	1	d3	d2	d1	d0

d0: Cursor blink on: 1, off: 0 d1: Cursor display on: 1, off: 0 d2: Text display on: 1, off: 0d3: Graphic display on:1, off:0

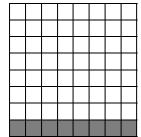
Note: It is necessary to turn on "Text display" and "Graphic display" in following case.

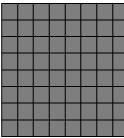
1) Combination of text/graphic display, 2) Attribute function.

• Cursor Pattern Select

Code	Function	Operand
10100000	1 line cursor	
10100001	2 lines cursor	
10100010	3 lines cursor	
10100011	4 lines cursor	
10100100	5 lines cursor	
10100101	6 lines cursor	
10100110	7 lines cursor	
10100111	8 lines cursor	

When cursor display is ON, this command selects the cursor pattern from 1 line to 8 lines. The cursor address is defined by cursor pointer set command.





1 line cursor

2 lines cursor

8 lines cursor

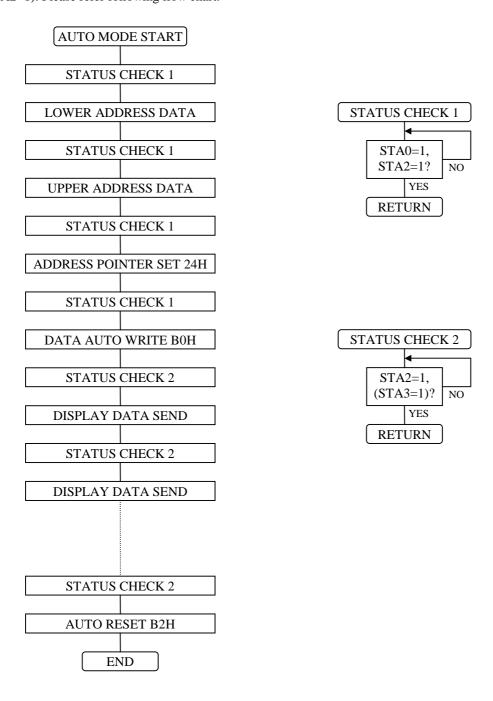


Data Auto Read/Write

Code	Hex	Hex Function			
10110000	B0H	Data auto write set			
10110001	B1H	Data auto read set			
10110010	B2H	Auto reset			

This command is convenient to send full screen data from external display RAM. After setting auto mode, "Data write (or read)" command is not necessary between each data. "Data auto write (or read)" command should follow the "Address pointer set" and address pointer is automatically increment by + 1 after each data. After sending (or receiving) all data "Auto reset" is necessary to return normal operation because all data is regarded "Display data" and no command can be accepted in the auto mode.

Note: Status check for auto mode (STA2,STA3) should be checked between each data. Auto reset should be performed after checking STA3=1 (STA2=1). Please refer following flow chart.



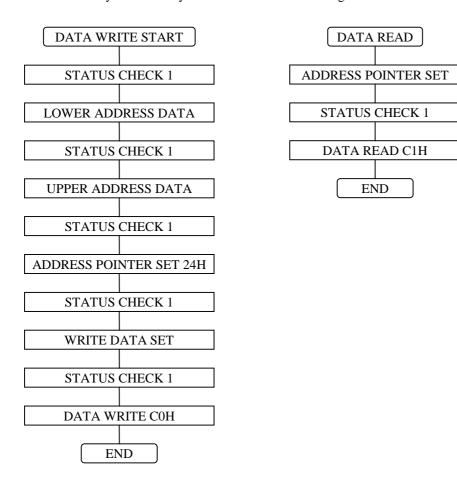


Data Read Write

Code	Hex	Function	Operand
11000000	C0H	Data write and ADP increment	Data
11000001	C1H	Data read and ADP increment	
11000010	C2H	Data write and ADP decrement	Data
11000011	СЗН	Data read and ADP decrement	
11000100	C4H	Data write and ADP nonvariable	Data
11000101	C5H	Data read and ADP nonvariable	

This command is used for data write from MPU to external display RAM, and data read from external display RAM to MPU. Data write/data read should be executed after setting address by address pointer set command. Address pointer can be automatically increment or decrement by setting this command.

Note: This command is necessary for each 1 byte data. Please refer following flow chart.



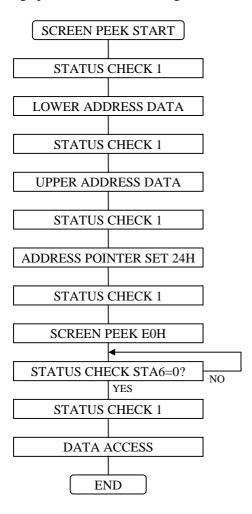


Screen Peek

Code	Hex	Function	Operand
11100000	E0H	Screen Peek	

This command is used to transfer displayed 1 byte data to data stack, and this 1 byte data can be read from MPU by data access. The logical combination data of text and graphic display on LCD screen can be read by this command.

The status (STA6) should be checked just after "Screen peek" command. If the address determined by "Address pointer Set" command is not in graphic area, this command ignored and status flag (STA6) is set. Please refer following flow chart.





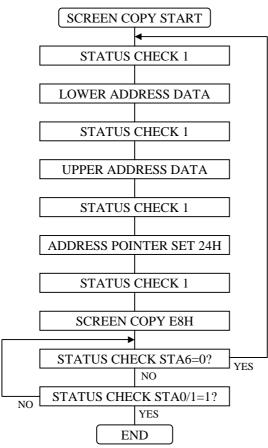
• Screen Copy

Code	Hex	Function	Operand
11101000	E8H	Screen copy	

This command is used to copy displayed 1 line data to graphic area. The start point of 1 line data in the screen is determined by the address pointer. Please refer following flow chart.

Note 1: In attribute function, this command is invalid. (Because attribute data is in the graphic area.)

Note 2: In case of 2 screen drive, this command is invalid. (Because T6963C cannot separate upper screen data and lower screen data.)

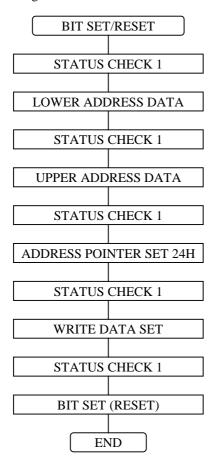




• Bit Set/Reset

Code	Function	Operand
11110xxx	bit reset	
11111xxx	bit set	
1111x000	bit 0 (LSB)	
1111x001	bit 1	
1111x010	bit 2	
1111x011	bit 3	
1111x100	bit 4	
1111x101	bit 5	
1111x110	bit 6	
1111x111	bit 7 (MSB)	

This command is used to set or reset a bit of 1 byte is specified by address pointer. Plural bits in the 1 byte data cannot be set/reset at a time. Please refer following flow chart.



Command List

Command	Code	D1	D2	Function
Register	00100001	X address	Y address	Cursor pointer set
Set	00100010	Data	00H	Offset register set
	00100100	Low address	High address	Address pointer set
	01000000	Low address	High address	Text home address set
Control	01000001	Columns	00H	Text area set
Word Set	01000010	Low address	High address	Graphic home address set
	01000011	Columns	00H	Graphic area set
	1000x000			"OR" mode
	1000x001			"EXOR" mode
Mode Set	1000x011			"AND" mode
	1000x100			"Text attribute" mode
	10000xxx			Internal CG ROM mode
	10001xxx			External CG RAM mode
	10010000			Display off
	1001xx10			Cursor on, blink off
Display	1001xx11			Cursor on, blink on
Mode	100101xx			Text on, graphic off
111000	100110xx			Text off, graphic on
	100110xx			Text on, graphic on
	10100000			1 line cursor
	10100000			2 lines cursor
Cursor	10100001			3 lines cursor
Pattern	10100010			4 lines cursor
Select	10100011			5 lines cursor
Select	10100100			6 lines cursor
	10100101			7 lines cursor
	10100110			8 lines cursor
Data Auto	10100111			Data auto write set
Read/Write				
Read/ Write	10110001			Data auto read set
	10110010			Auto reset
	11000000	Data		Data write and ADP increment
D . D . I	11000001			Data read and ADP increment
Data Read	11000010	Data		Data write and ADP decrement
Write	11000011			Data read and ADP decrement
	11000100	Data		Data write and ADP nonvariable
	11000101			Data read and ADP nonvariable
Screen Peek	11100000			Screen peek
Screen Copy	11101000			Screen copy
	11110xxx			bit reset
	11111xxx			bit set
	1111x000			bit 0 (LSB)
Bit	1111x001			bit 1
Set/Reset	1111x010			bit 2
	1111x011			bit 3
	1111x100			bit 4
	1111x101			bit 5
	1111x110			bit 6
	1111x111			bit 7 (MSB)



Character Code Map

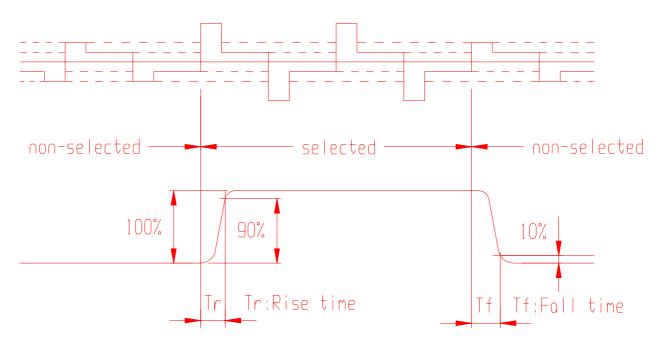
ROM CODE 0101

MZB TZB	0	1	2	3	4	5	6	7	8	9	А	В	С	D	Е	F
0								E				22555		2222		
1																
2									-							
3																
4																
5																
6																
7																

■ ELECTRO-OPTICAL CHARACTERISTICS (Vop = 17.5V, Ta = 25°C)

Item	Symbol	Condition	Min	Тур	Max	Unit	Remarks	Note
Response time	Tr			200		ms		1
	Tf			246		ms		1
Contrast ratio	Cr			7.4				2
			44			deg	Ø = 90°	3
Viewing angle range	θ	Cr ≥ 2	49			deg	Ø = 270°	3
			42			deg	Ø = 0°	3
			37			deg	Ø = 180°	3

Note1: Definition of response time.



Note2: Definition of contrast ratio 'Cr'.

Brightness of non-selected segment(B2)

Brightness of selected segment(B1)

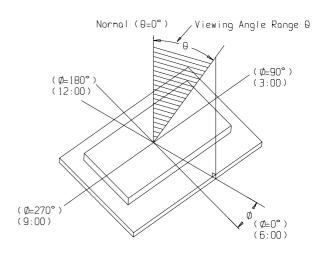
Brightness curve for non-selected segment

Brightness curve for selected segment

Brightness curve for selected segment

Oriving Voltage

Note3: Definition of viewing angle range ' θ '.





■ INTERFACE PIN CONNECTIONS

Pin No.	Symbol	Level	Description
1	FG	0V	Frame ground
2	VSS	0V	Ground
3	VDD	5.0V	Supply voltage for logic
4	(V0)		Input voltage for LCD
5	WR	L	Write signal
6	RD	L	Read signal
7	CE	L	Chip enable signal
8	C/D	H/L	H: Instruction Code, L: Data
9	RET	L	Reset signal
10	DB0	H/L	Data bit 0
11	DB1	H/L	Data bit 1
12	DB2	H/L	Data bit 2
13	DB3	H/L	Data bit 3
14	DB4	H/L	Data bit 4
15	DB5	H/L	Data bit 5
16	DB6	H/L	Data bit 6
17	DB7	H/L	Data bit 7
18	FS	H/L	Font select signal (H: 6 x 8 dots, L: 8 x 8 dots)
19	VOUT	-15V	Output voltage for LCD
20	BLA	+5V	Supply voltage for LED
21	BLK	GND	Ground
22	NC	NC	NC

■ RELIABILITY

Content of Reliability Test

	Environmental Test									
No.	Test Item	Content of Test	Test Condition	Applicable Standard						
1	High temperature	Endurance test applying the high storage	60 °C							
	storage	temperature for a long time.	200 hrs							
2	Low temperature	Endurance test applying the low storage	-10 °C							
	storage	temperature for a long time.	200 hrs							
3	High temperature	Endurance test applying the electric stress	50 °C							
	operation	(Voltage & Current) and the thermal stress to the element for a long time.	200 hrs							
4	Low temperature	Endurance test applying the electric stress under	0 °C							
	operation	low temperature for a long time.	200 hrs							
5	High temperature /	Endurance test applying the high temperature	60 °C, 90 %RH	MIL-202E-103B						
	Humidity storage	and high humidity storage for a long time.	96 hrs	JIS-C5023						
6	High temperature /	Endurance test applying the electric stress	40 °C, 90 %RH	MIL-202E-103B						
	Humidity operation	(Voltage & Current) and temperature / humidity	96 hrs	JIS-C5023						
		stress to the element for a long time.								
7	Temperature cycle	Endurance test applying the low and high	-10°C / 60°C							
		temperature cycle.	10 cycles							
		-10°C 25°C 60°C								
		$\frac{-10^{\circ}\text{C}}{30\text{min}} \rightleftharpoons \frac{25^{\circ}\text{C}}{5\text{min.}} \rightleftharpoons \frac{60^{\circ}\text{C}}{30\text{min}}$								
		← → 1 cycle								
	l	Mechanical Test								
8	Vibration test	Endurance test applying the vibration during	$10\sim22$ Hz → 1.5 mmp-p	MIL-202E-201A						
		transportation and using.	$22\sim500$ Hz $\to 1.5$ G	JIS-C5025						
			Total 0.5hrs	JIS-C7022-A-10						
9	Shock test	Constructional and mechanical endurance test	50G half sign	MIL-202E-213B						
		applying the shock during transportation.	wave 11 msedc							
			3 times of each direction							
10	Atmospheric pressure	Endurance test applying the atmospheric	115 mbar	MIL-202E-105C						
	test	pressure during transportation by air.	40 hrs							
		Others								
11	Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V , RS=1.5 kΩ CS=100 pF	MIL-883B-3015.1						

^{***} Supply voltage for logic system = 5V. Supply voltage for LCD system = Operating voltage at 25°C.

Failure Judgement Criterion

- william of war gains and control of the control o												
Criterion Item		Test Item No.							Failure Judgment Criterion			
	1	2	3	4	5	6	7	8	9	10	11	
Basic specification												Out of the Basic Specification
Electrical characteristic												Out of the DC and AC Characterstic
Mechanical characterstic												Out of the Mechanical Specification Color
												change: Out of Limit Apperance Specification
Optical characterstic												Out of the Apperance Standard

■ QUALITY GUARANTEE

Acceptable Quality Level

Each lot should satisfy the quality level defined as follows.

- Inspection method: MIL-STD-105E LEVEL II Normal one time sampling
- AQL

Partition	AQL	Definition
A: Major	0.4%	Functional defective as product
B: Minor	1.5%	Satisfy all functions as product but not satisfy cosmetic standard

Definition of 'LOT'

One lot means the delivery quantity to customer at one time.

Conditions of Cosmetic Inspection

• Environmental condition

The inspection should be performed at the 1m of height from the LCD module under 2 pieces of 40W white fluorescent lamps (Normal temperature $20\sim25$ °C and normal humidity 60 ± 15 %RH).

- Inspection method
 - The visual check should be performed vertically at more than 30cm distance from the LCD panel.
- Driving voltage

The V_0 value which the most optimal contrast can be obtained near the specified V_0 in the specification. (Within $\pm 0.5V$ of the typical value at 25°C.).

■ INSPECTION CRITERIA

Module Cosmetic Criteria

Item	Judgement Criterion	Partition
Difference in Spec.	None allowed	Major
Pattern peeling	No substrate pattern peeling and floating	Major
Soldering defects	No soldering missing	Major
	No soldering bridge	Major
	No cold soldering	Minor
Resist flaw on substrate	Invisible copper foil (Ø0.5mm or more) on substrate pattern	Minor
Accretion of metallic	No soldering dust	Minor
Foreign matter	No accretion of metallic foreign matters (Not exceed Ø0.2mm)	Minor
Stain	No stain to spoil cosmetic badly	Minor
Plate discoloring	No plate fading, rusting and discoloring	Minor
Solder amount	a. Soldering side of PCB	Minor
	Solder to form a 'Filet'	
1. Lead parts	all around the lead.	
	Solder should not hide the	
	(In case of 'Through Hole PCB')	
	Solder to reach the Components side of PCB.	
2. Flat packages	Either 'toe' (A) or 'heal' (B) of	Minor
	the lead to be covered by 'Filet'.	
	Lead form to be assume over solder.	
3. Chips	$(3/2) H \ge h \ge (1/2) H$	Minor
	Difference in Spec. Pattern peeling Soldering defects Resist flaw on substrate Accretion of metallic Foreign matter Stain Plate discoloring Solder amount 1. Lead parts 2. Flat packages	Difference in Spec. None allowed Pattern peeling No substrate pattern peeling and floating Soldering defects No soldering missing No soldering bridge No cold soldering Resist flaw on substrate Invisible copper foil (∅0.5mm or more) on substrate pattern Accretion of metallic Foreign matter No soldering dust No soldering dust No accretion of metallic foreign matters (Not exceed ∅0.2mm) Stain No stain to spoil cosmetic badly Plate discoloring No plate fading, rusting and discoloring Solder amount a. Soldering side of PCB Solder to form a 'Filet' all around the lead. Solder should not hide the lead form perfectly. (too much) b. Components side (In case of 'Through Hole PCB') Solder to reach the Components side of PCB. 2. Flat packages Either 'toe' (A) or 'heal' (B) of the lead to be covered by 'Filet'. Lead form to be assume over solder. 3. Chips (3/2) H ≥ h ≥ (1/2) H

Screen Cosmetic Criteria (Non-Operating)

No.	Defect	Jud	Partition						
1	Spots	In accordance with Screen Cosn	Minor						
2	Lines	In accordance with Screen Cosn	Minor						
3	Bubbles in polarizer	Size: d mm $d \le 0.3$ $0.3 < d \le 1.0$ $1.0 < d \le 1.5$ 1.5 < d	$\begin{array}{cccc} d \leq 0.3 & & \text{Disregard} \\ 0.3 < d \leq 1.0 & & 3 \\ 1.0 < d \leq 1.5 & & 1 \end{array}$						
4	Scratch	In accordance with spots and lines operating cosmetic criteria. When the light reflects on the panel surface, the scratches are not to be remarkable.							
5	Allowable density	Above defects should be separat	Above defects should be separated more than 30mm each other.						
6	Coloration	Not to be noticeable coloration	Minor						
		Back-lit type should be judged v							
7	Contamination	Not to be noticeable.	Minor						

Screen Cosmetic Criteria (Operating)

No.	Defect		ent Criterion	Partition
1	Spots	A) Clear	Acceptable Qty in active area Disregard 6 2 0 tive dots which must be within one pixel	Minor
		Size: d mm $d \le 0.2$ $0.2 < d \le 0.5$ $0.5 < d \le 0.7$ $0.7 < d$	Acceptable Qty in active area Disregard 6 2 0	
2	Lines	A) Clear L 5.0 2.0 (6) 0.02 0.05 Note: () - Acceptable Qty in active L - Length (mm)	(0) See No. 1 0.1 W	Minor
		W - Width (mm) ∞ - Disregard B) Unclear L 10.0 ∞ (6)	(0) See No. 1	

^{&#}x27;Clear' = The shade and size are not changed by Vo.

^{&#}x27;Unclear' = The shade and size are changed by $V_{\rm O}$.



Screen Cosmetic Criteria (Operating) (Continued)

No.	Defect	Judgement Criterion	Partition
3	Rubbing line	Not to be noticeable.	
4	Allowable density	Above defects should be separated more than 10mm each other.	Minor
5	Rainbow	Not to be noticeable.	Minor
6	Dot size	To be 95% ~ 105% of the dot size (Typ.) in drawing. Partial defects of each dot (ex. pin-hole) should be treated as 'spot'. (see Screen Cosmetic Criteria (Operating) No.1)	Minor
7	Uneven brightness (only back-lit type module)	Uneven brightness must be BMAX / BMIN ≤ 2 - BMAX : Max. value by measure in 5 points - BMIN : Min. value by measure in 5 points Divide active area into 4 vertically and horizontally. Measure 5 points shown in the following figure.	Minor
		O : Measuring points	

Note:

- (1) Size : d = (long length + short length) / 2
- (2) The limit samples for each item have priority.
- (3) Complexed defects are defined item by item, but if the number of defects are defined in above table, the total number should not exceed 10.
- (4) In case of 'concentration', even the spots or the lines of 'disregarded' size should not allowed. Following three situations should be treated as 'concentration'.
 - 7 or over defects in circle of Ø5mm.
 - 10 or over defects in circle of Ø10mm.
 - 20 or over defects in circle of Ø20mm.

■ PRECAUTIONS FOR USING LCD MODULES

Handing Precautions

- (1) The display panel is made of glass. Do not subject it to a mechanical shock by dropping it or impact.
- (2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
 - (3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
 - (4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- (5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol
 - (6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
 - Water
 - Ketone
 - Aromatic solvents
- (7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.

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SHENZHEN TECHSTAR ELECTRONICS CO.,LTD

- (8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
 - (9) Do not attempt to disassemble or process the LCD module.
 - (10) NC terminal should be open. Do not connect anything.
 - (11) If the logic circuit power is off, do not apply the input signals.
 - (12) To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Be sure to ground the body when handling the LCD modules.
 - Tools required for assembling, such as soldering irons, must be properly grounded.
 - To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions.
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

Storage Precautions

When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps. Keep the modules in bags (avoid high temperature / high humidity and low temperatures below 0°C). Whenever possible, the LCD modules should be stored in the same conditions in which they were shipped from our company.

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
- Terminal electrode sections.

■ USING LCD MODULES

Liquid Crystal Display Modules

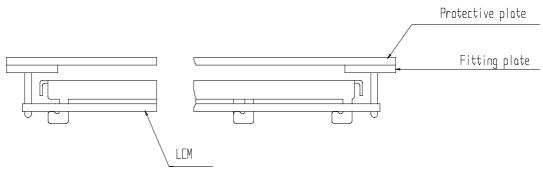
LCD is composed of glass and polarizer. Pay attention to the following items when handling.

- (1) Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.
 - (2) Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.).
- (3) N-hexane is recommended for cleaning the adhesives used to attach front/rear polarizers and reflectors made of organic substances which will be damaged by chemicals such as acetone, toluene, ethanol and isopropylalcohol.
- (4) When the display surface becomes dusty, wipe gently with absorbent cotton or other soft material like chamois soaked in petroleum benzin. Do not scrub hard to avoid damaging the display surface.
- (5) Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading.
 - (6) Avoid contacting oil and fats.
- (7) Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizers. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.
 - (8) Do not put or attach anything on the display area to avoid leaving marks on.
- (9) Do not touch the display with bare hands. This will stain the display area and degradate insulation between terminals (some cosmetics are determinated to the polarizers).
 - (10) As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring.

Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

(1) Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



(2) When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ± 0.1 mm.

Precaution for Handing LCD Modules

Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

- (1) Do not alter, modify or change the the shape of the tab on the metal frame.
- (2) Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- (3) Do not damage or modify the pattern writing on the printed circuit board.
- (4) Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- (5) Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- (6) Do not drop, bend or twist LCM.

Electro-Static Discharge Control

Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC.

- (1) Make certain that you are grounded when handing LCM.
- (2) Before remove LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential.
 - (3) When soldering the terminal of LCM, make certain the AC power source for the soldering iron does not leak.
- (4) When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
 - (5) As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.
- (6) To reduce the generation of static electricity be careful that the air in the work is not too dried. A relative humidity of 50%-60% is recommended.

Precaution for soldering to the LCM

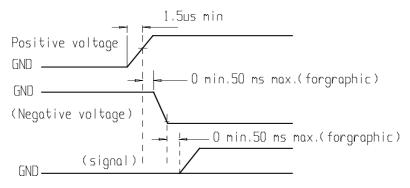
- (1) Observe the following when soldering lead wire, connector cable and etc. to the LCM.
 - Soldering iron temperature : $280^{\circ}\text{C} \pm 10^{\circ}\text{C}$.
 - Soldering time : 3-4 sec.
 - Solder : eutectic solder.

If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage dur to flux spatters.

- (2) When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.
- (3) When remove the electoluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

Precautions for Operation

- (1) Viewing angle varies with the change of liquid crystal driving voltage (Vo). Adjust Vo to show the best contrast.
- (2) Driving the LCD in the voltage above the limit shortens its life.
- (3) Response time is greatly delayed at temperature below the operating temperature range. However, this does not mean the LCD will be out of the order. It will recover when it returns to the specified temperature range.
- (4) If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.
- (5) Condensation on terminals can cause an electrochemical reaction disrupting the terminal circuit. Therefore, it must be used under the relative condition of 40° C, 50% RH.
 - (6) When turning the power on, input each signal after the positive/negative voltage becomes stable.



Storage

When storing LCDs as spares for some years, the following precaution are necessary.

- (1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for dessicant.
- (2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C.
- (3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the container in which they were shipped.)
 - (4) Environmental conditions:
 - Do not leave them for more than 168hrs. at 60°C.
 - Should not be left for more than 48hrs. at -20°C.

Safety

- (1) It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.
 - (2) If any liquid leakes out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

Limited Warranty

Unless agreed between TRULY and customer, TRULY will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with TRULY LCD acceptance standards (copies available upon request) for a period of one year from date of shipments. Cosmetic/visual defects must be returned to TRULY within 90 days of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of TRULY limited to repair and/or replacement on the terms set forth above. TRULY will not be responsible for any subsequent or consequential events.

Return LCM under warranty

No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :

- Broken LCD glass.
- PCB eyelet's damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- soldering to or modifying the bezel in any manner.

Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet's, conductors and terminals.